



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR SSOT-23					
STRESS	SAMPLE SIZE	DEVICE HR./CYC	CONDITION	TOTAL FAILS	FAIL PERCENTAGE
BOND INT	360	180,000	200 °C + N2	0	0.00
HAST	1718	169,300	130 °C, 85 % RH	0	0.00
Power Cycle	428	4,917,096	DELTA T _j = 100	0	0.00
Pressure Pot	5396	527,616	121°, 15 PSIG	0	0.00
Solder Dunk	1280	3,940	260 °C, 10 s	0	0.00
Solderability	715	6,230	883 M2003	0	0.00
Temp. Cycle	5653	2,935,750	- 65 °C to 150 °C	0	0.00